

# The Progress of GEM foil at CIAE

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#### Outline

#### The progress of GEM foil at CIAE

#### Other developments at CIAE

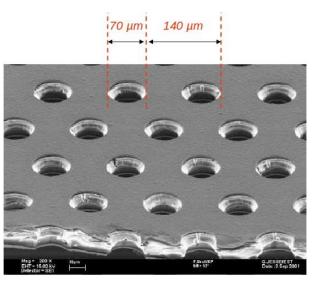


# The Progress of GEM Foil at CIAE

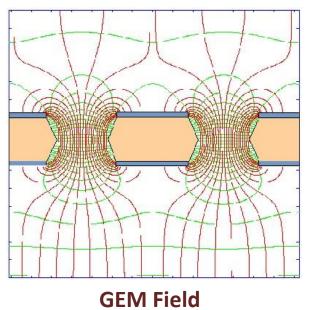


#### **GEM Foil Structure**

- Typical GEM Foil has 3 layers, two 5µm thick copper foils and one 50µm thick kapton foil in the middle.
- Diameter of the hole is 70 μm , and the distance between them is 140 μm .
- 3. Apply electric voltages on the two copper layers.
- 4. Electric Field is very strong in the hole area, and weak outside the hole area.



**GEM Foil** 



#### **Clean Room**



The cleanrooms at China Institute of Atomic Energy are ISO Class 6.

# Photolithography Lab Construction At CIAE









# The Equipments for Lamination and Exposure of Dry Film Photoresist



Lamination and exposure of dry film photoresist are the most important and difficult steps for GEM foil production.



We have established a yellow light zone, and have introduced Hot Roll Lamination (HRL) machine and Exposure system.

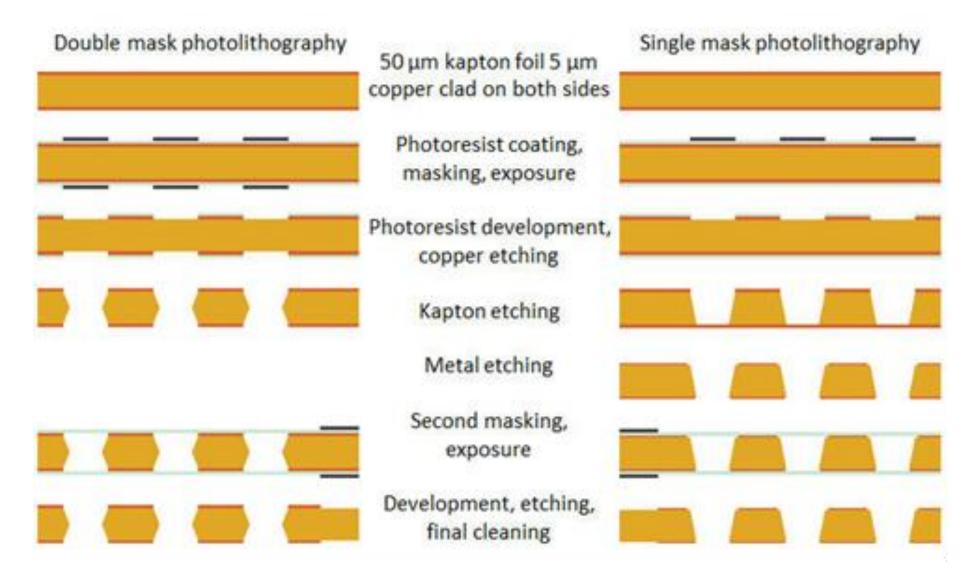
We invited the Senior engineer from a famous electronic factory to CIAE and taught the PCB technology.

### **Etching Room Construction**

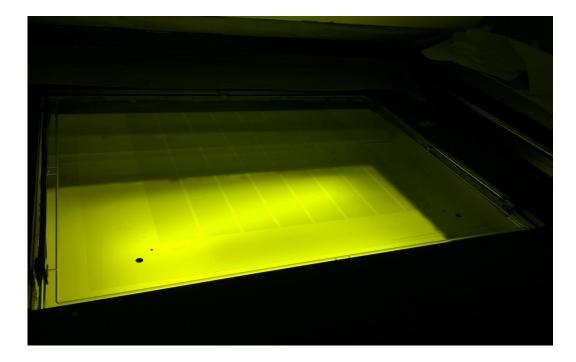




#### The Procedure of GEM Foil

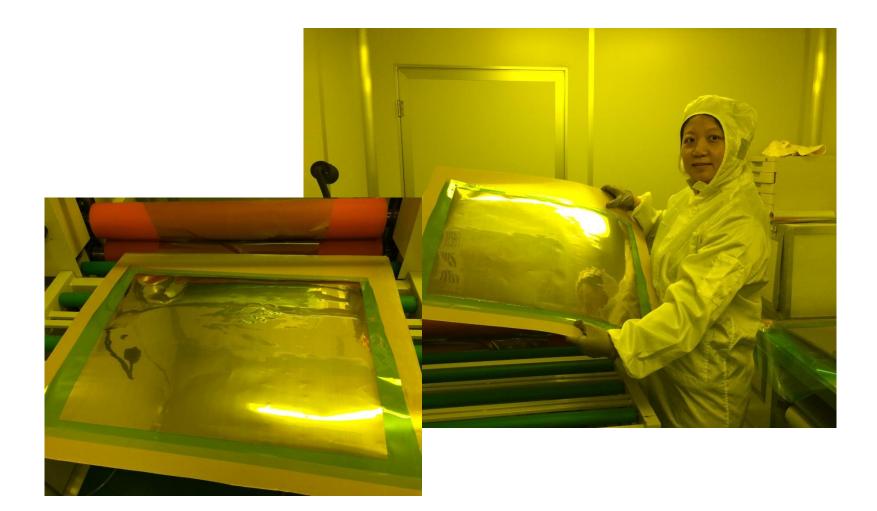


#### **GEM Photo Mask Plate**



The copies of the photo-mask are done by photolithographic techniques. 40cm\*40cm photo mask is produced.

### **Lamination of Dry Film Photoresist**



# **Exposure of Dry Film Photoresist**



# **After First Copper Etching**

50 µm kapton foil 5 µm copper clad on both sides

Photoresist coating, masking, exposure

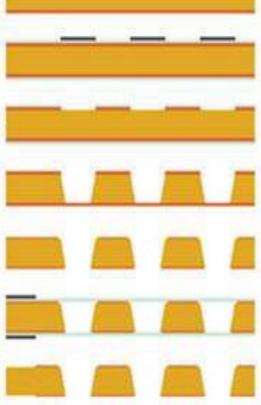
Photoresist development, copper etching

Kapton etching

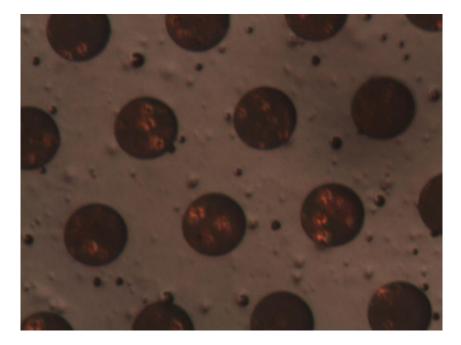
Metal etching

Second masking, exposure

Development, etching, final cleaning



Single mask photolithography



# **After First Kapton Etching**

50 µm kapton foil 5 µm copper clad on both sides

Photoresist coating, masking, exposure

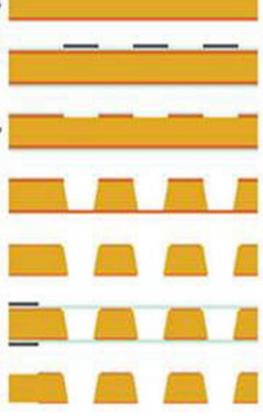
Photoresist development, copper etching

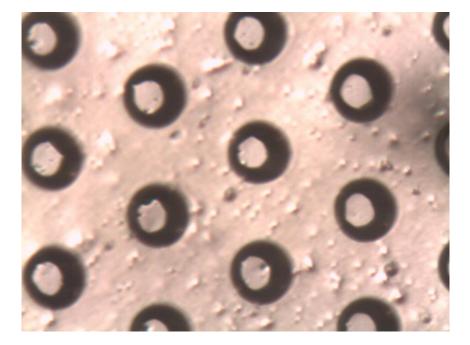
Kapton etching

Metal etching

Second masking, exposure

Development, etching, final cleaning Single mask photolithography





# **After Second Copper Etching**

50 µm kapton foil 5 µm copper clad on both sides

Photoresist coating, masking, exposure

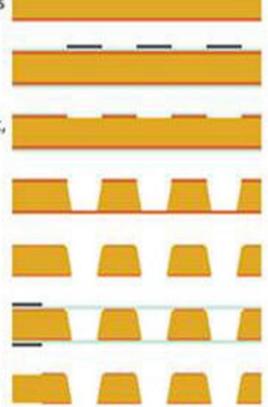
Photoresist development, copper etching

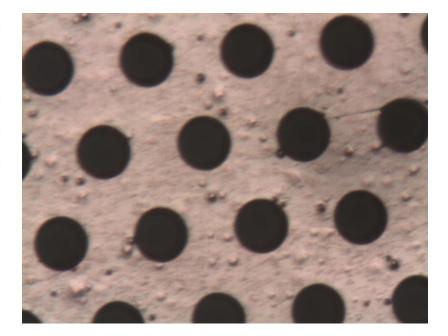
Kapton etching

Metal etching

Second masking, exposure

Development, etching, final cleaning Single mask photolithography

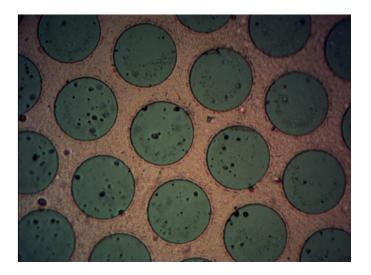


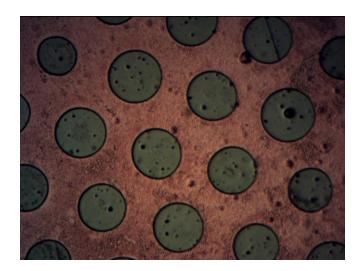


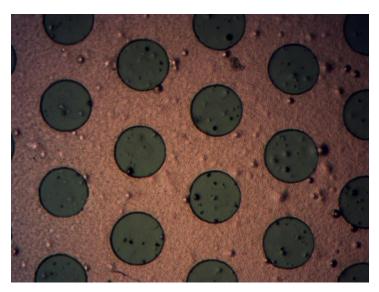
#### 40cm\*40cm GEM Foil

The 40cm\*40cm GEM foils were made successfully.
Single-mask method was used.

#### **New Chemical Reagents**







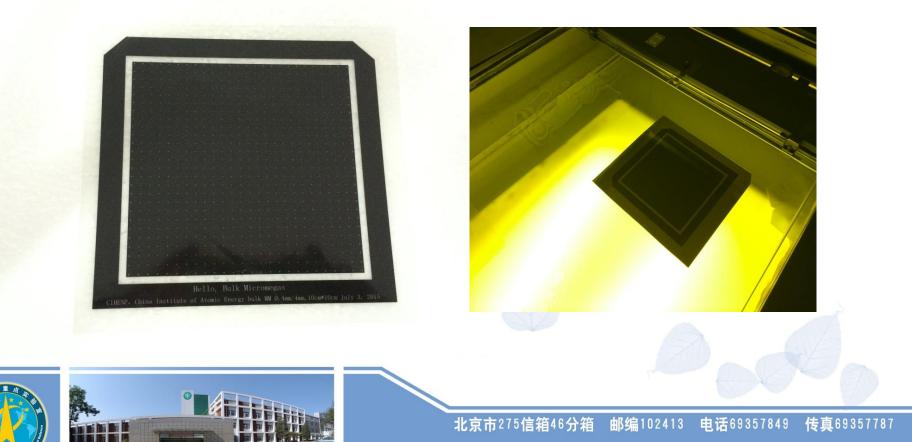


# **Other Developments**



### **R&D of Bulk MicroMegas**

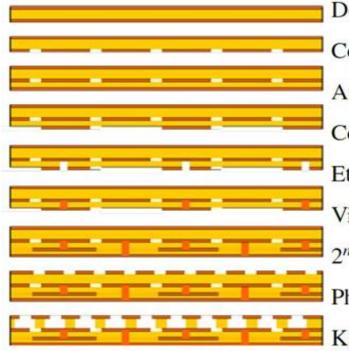
#### Based on the Collaboration with CEPC TPC (IHEP)



# **R&D of MicroBulk MicroMegas**

#### **Microbulk Micromegas Fabrication Process**

This technology is inspired by the GEM detector fabrication process invented at CERN .

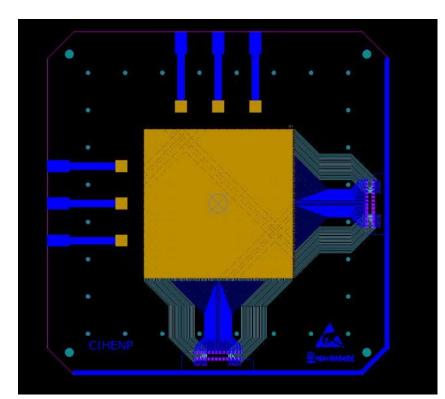


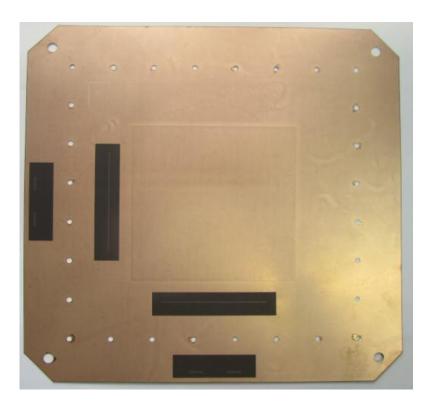
Double side Cu-coated (5  $\mu$ m) Kapton foil (50  $\mu$ m), Construction of readout strips/pads (photolithography) Attachment of a single-side Cu-coated kapton foil (25/5  $\mu$ m) Construction of readout lines Etching of kapton Vias construction  $2^{nd}$  Layer of Cu-coated kapton Photochemical production of mesh holes

Kapton etching / Cleaning

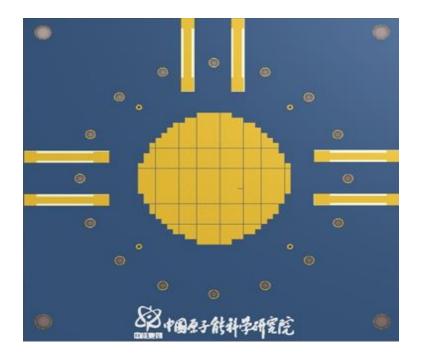
#### Current Work on MicroBulk MicroMegas

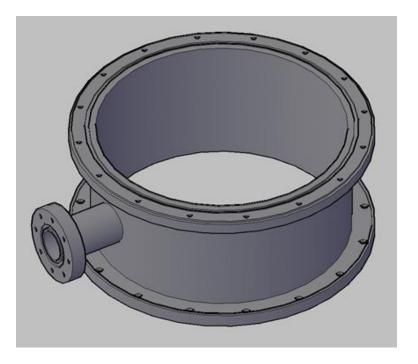
Based on the Collaboration with PANDAXIII(SJTU) New design of 10cm\*10cm MicroBulk MicroMegas Prototype: XY readout, 200 channels electronics

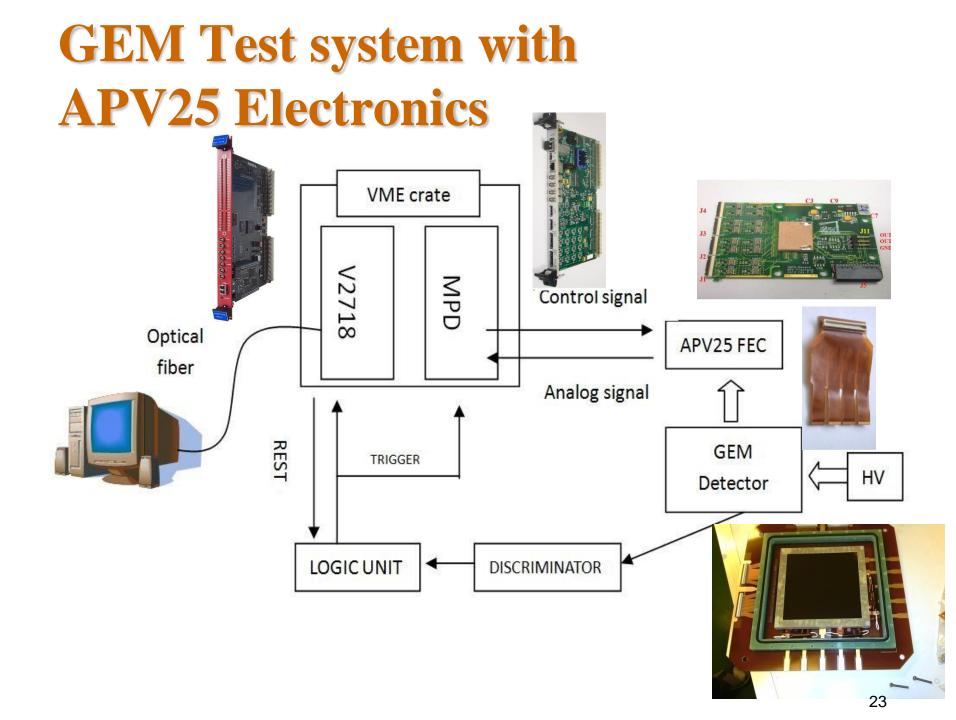




**Next Step on on MicroBulk MicroMegas** New design of 20cm diameter round MicroBulk MicroMegas Prototype: 0.5cm<sup>2</sup> pad, 512 channels electronics

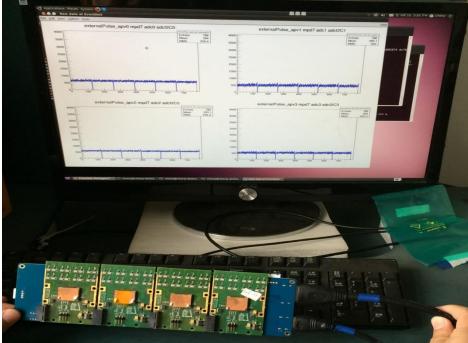






#### **R&D of BackPlane**





### **Next Step**

•Made 30cm\*30cm and 40cm\*40cm GEM foils by using double mask and single mask technologies respectively.

•Upgrading current equipment and improving the rate of final products.

#### •Establishing collaboration with company.



# Thank You !

